# PRODUCT / PROCESS CHANGE NOTIFICATION

## 1. PCN basic data

| | | |
|---|---|---|
| **1.1 Company** | | STMicroelectronics International N.V |
| **1.2 PCN No.** | | AMS/20/11886 |
| **1.3 Title of PCN** | | New molding compound for DIP package to replace SAMSUNG SDI under termination phase |
| **1.4 Product Category** | | See product list |
| **1.5 Issue date** | | 2020-01-28 |

## 2. PCN Team

| | |
|---|---|
| **2.1 Contact supplier** | |
| **2.1.1 Name** | NEMETH KRISZTINA |
| **2.1.2 Phone** | +49 89460062210 |
| **2.1.3 Email** | krisztina.nemeth@st.com |
| **2.2 Change responsibility** | |
| **2.2.1 Product Manager** | Domenico ARRIGO,Marcello SAN BIAGIO |
| **2.1.2 Marketing Manager** | Salvatore DI VINCENZO,Fulvio PULICELLI |
| **2.1.3 Quality Manager** | Sergio Tommaso SPAMPINATO,Alessandro PLATINI |

## 3. Change

| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
|---|---|---|
| Materials | New direct material part number (same supplier, different supplier or new supplier), Mold compound | Assembly = Nantong Fujitsu (China) |

## 4. Description of change

| | Old | New |
|---|---|---|
| **4.1 Description** | Molding compound = Samsung SG8200DTA | Molding compound = Replacement of current molding compounds with alternative material from different supplier (see qualification report for more details) |
| **4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?** | No impact | |

## 5. Reason / motivation for change

| | |
|---|---|
| **5.1 Motivation** | As stated in the ST Corporate Product Change Information CRP/19/11478, the current molding compound supplied by Samsung will be terminated. So the goal of this PCN is to announce the qualification of a new molding compound for products in DIP package assembled in Nantong Fujitsu (China).<br>The changed products do not present modified electrical, dimensional or thermal parameters, leaving unchanged the current information published in the product datasheet. There is no change in the packing modes and the standard delivery quantities either. |
| **5.2 Customer Benefit** | SERVICE CONTINUITY |

## 6. Marking of parts / traceability of change

| | |
|---|---|
| **6.1 Description** | New Finished good codes |

## 7. Timing / schedule

| | |
|---|---|
| **7.1 Date of qualification results** | 2019-12-15 |
| **7.2 Intended start of delivery** | 2020-05-01 |
| **7.3 Qualification sample available?** | Upon Request |

## 8. Qualification / Validation

| | |
|---|---|
| **8.1 Description** | 11886 Qual report.zip |

| | | | |
|---|---|---|---|
| **8.2 Qualification report and qualification results** | Available (see attachment) | **Issue Date** | 2020-01-28 |

| **9. Attachments (additional documentations)** |
|---|
| 11886 Public product.pdf<br>11886 Qual report.zip |

| **10. Affected parts** | | |
|---|---|---|
| **10. 1 Current** | | **10.2 New (if applicable)** |
| **10.1.1 Customer Part No** | **10.1.2 Supplier Part No** | **10.1.2 Supplier Part No** |
| | L6561 | |
| MC34063ACN | MC34063ACN | |
| UC2842BN | UC2842BN | |
| UC3843BN | UC3843BN | |
| | UC3844BN | |
| | UC3845BN | |
| | VIPER17LN | |

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# Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

***PCN Title :*** New molding compound for DIP package to replace SAMSUNG SDI under termination phase
***PCN Reference :*** AMS/20/11886

***Subject :*** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

| | | |
|---|---|---|
| VIPER16HN | VIPER35LE | VIPER38LE |
| MC34063ABN | MC34063ACN | UC2844BN |
| UC3842BN | L4978 | TDE1798DP |
| UC3843BN | L4971 | VIPER26LN |
| VIPER37LE | UC2843BN | VIPER17HN |
| L4976 | VIPER25LN | VIPER28LN |
| VIPER27HN | VIPER38HE | VIPER27LN |
| L6565N | VIPER28HN | VIPER06HN |
| MC34063EBN | MC34063ECN | UC3844BN |
| VIPER26HN | UC2845BN | VIPER06LN |
| VIPER06XN | VIPER17LN | UC2842BN |
| VIPER25HN | UC3845BN | VIPER35HE |
| L6562AN | L6561 | L6562N |
| VIPER37HE | | |

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